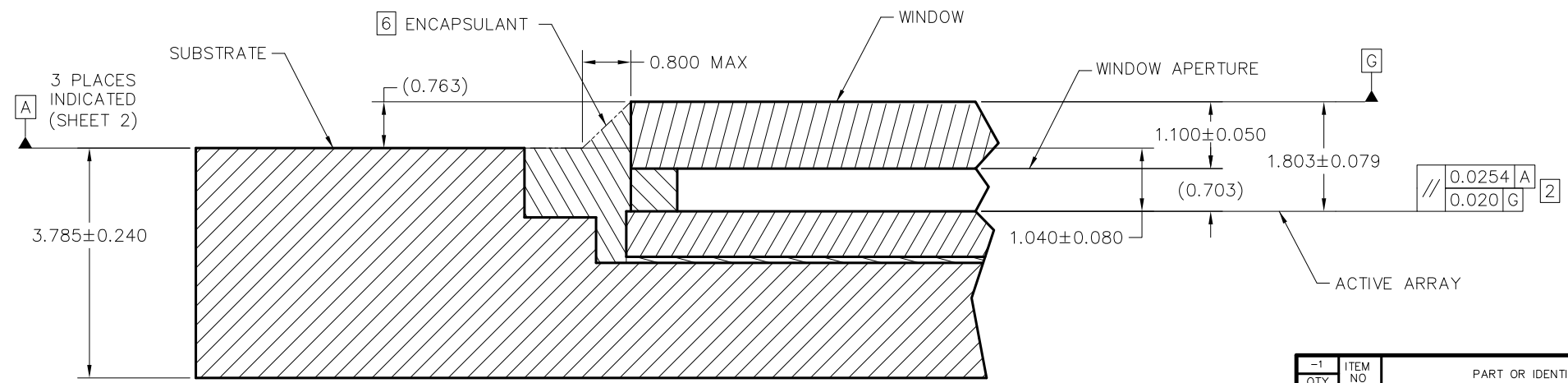
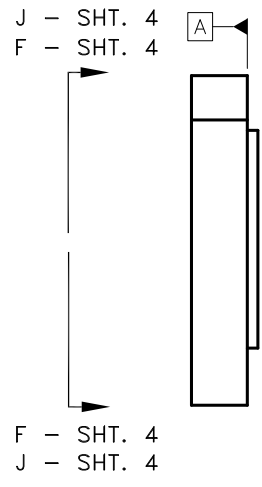
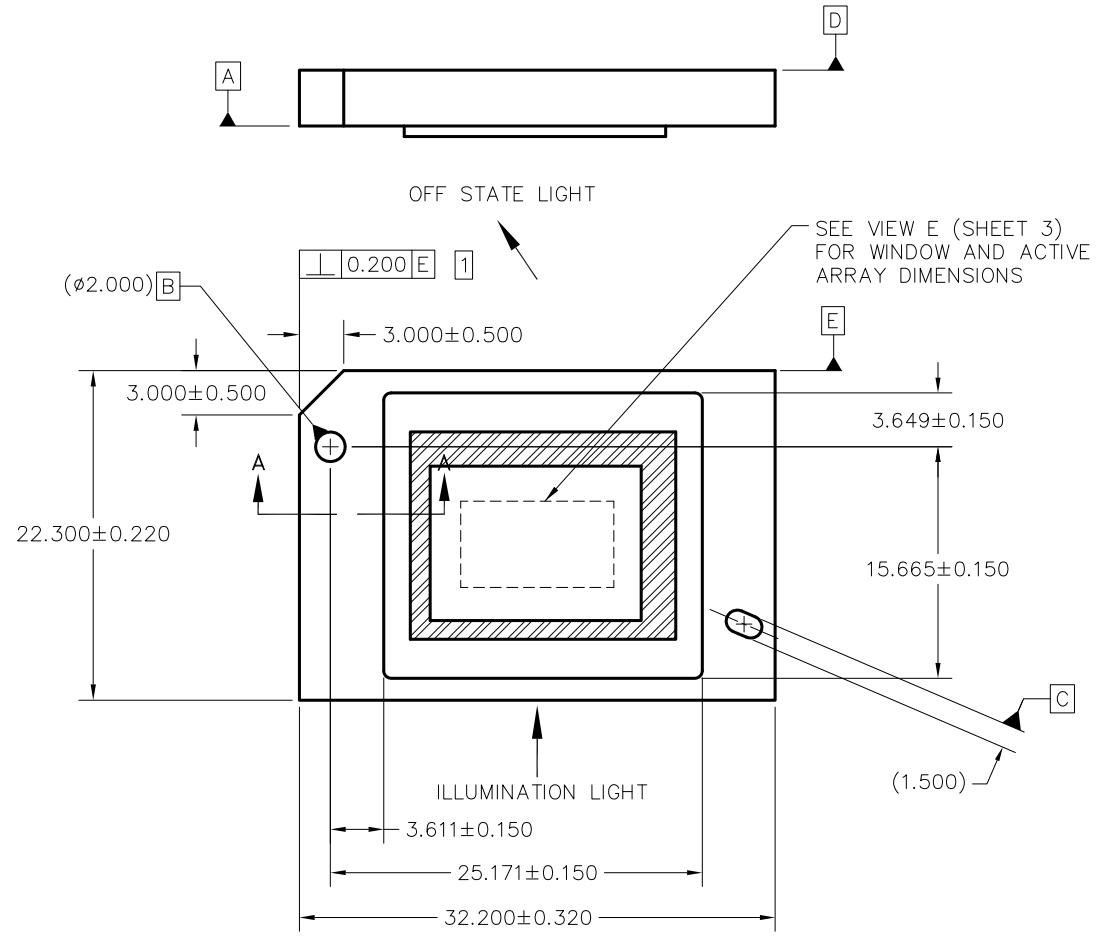


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2159772, INITIAL RELEASE	07/28/2016	F. ARMSTRONG
B	ECO 2163097, CORRECT POM Y-DIRECTION DIMS	12/15/2016	F. ARMSTRONG

NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 SUBSTRATE EDGE PERPENDICULARITY TOLERANCE APPLIES TO ENTIRE SURFACE
- 2 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY
- 3 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.8 DEGREES
- 4 SUBSTRATE SYMBOLIZATION PAD, AND PLATING AT BOTTOM OF DATUMS B AND C HOLES TO BE ELECTRICALLY CONNECTED TO VSS PLANE WITHIN THE SUBSTRATE
- 5 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE AREA
- 6 MAXIMUM ENCAPSULANT PROFILE SHOWN
- 7 ENCAPSULANT ALLOWED ON THE SURFACE OF THE CERAMIC IN THE AREA SHOWN IN VIEW B (SHEET 2). ENCAPSULANT SHALL NOT EXCEED 0.200 THICKNESS MAXIMUM.
- 8 SUBSTRATES PLATED WITH Ni/Au SHALL HAVE THE THREE-DIGIT NUMERICAL MARKING IN THE AREA TO THE LEFT OF THE SYMBOLIZATION PAD. SUBSTRATES PLATED WITH Ni/Pd/Au SHALL HAVE THE MARKING IN THE AREA TO THE RIGHT OF THE SYMBOLIZATION PAD.



SECTION A-A
SCALE 20/1

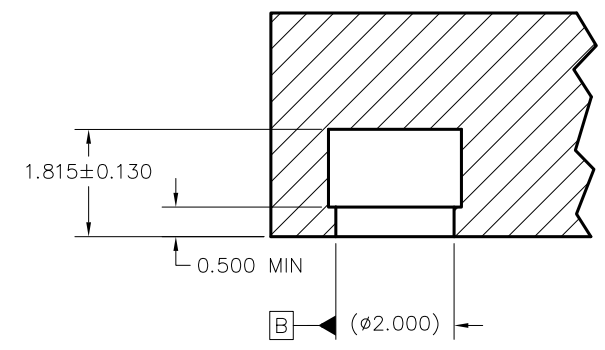
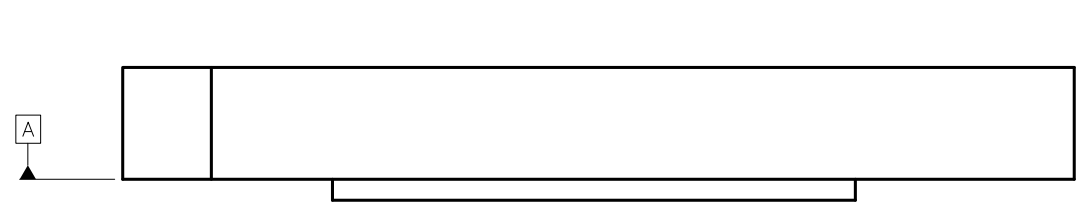
QTY	ITEM NO	PART OR IDENTIFYING NUMBER	NOMENCLATURE OR DESCRIPTION	NOTES
-1				

PARTS LIST		DATE		DRAWING NO	
ENGR	F. ARMSTRONG	07/13/16		2515169	REV B
QA	P. KONRAD	08/03/16			
COE	M. DORAK	08/03/16			

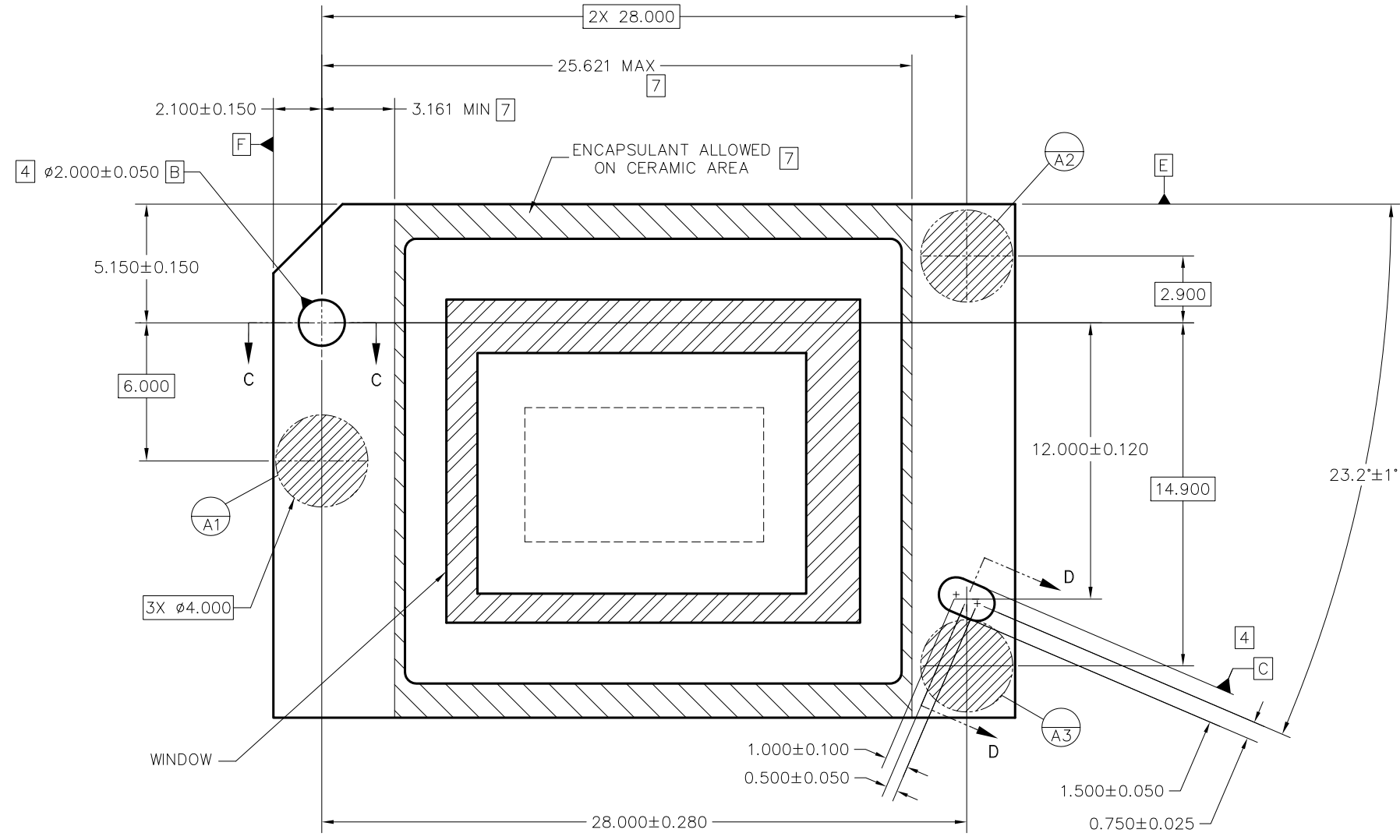
UNLESS OTHERWISE SPECIFIED	DIMENSIONS ARE IN MILLIMETERS
TOLERANCES: ANGLES ± 1°	2 PLACE DECIMALS ±0.25
	3 PLACE DECIMALS ±0.50
REMOVE ALL BURRS AND SHARP EDGES	INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5-1994
DIMENSIONAL LIMITS APPLY BEFORE PROCESSES	PARENTHEICAL INFO FOR REF ONLY

THIRD ANGLE PROJECTION	NONE	0314DA
NEXT ASSY	USED ON	
APPLICATION		

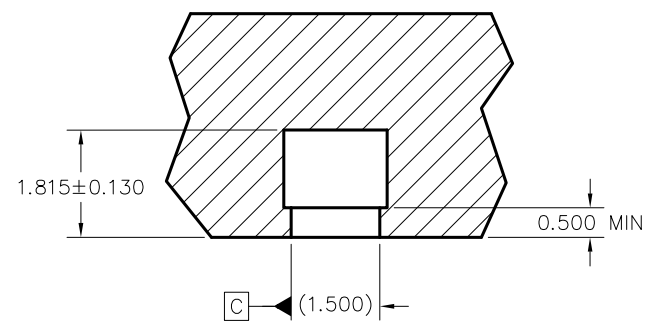
SCALE	4/1	SHEET	1 OF 4
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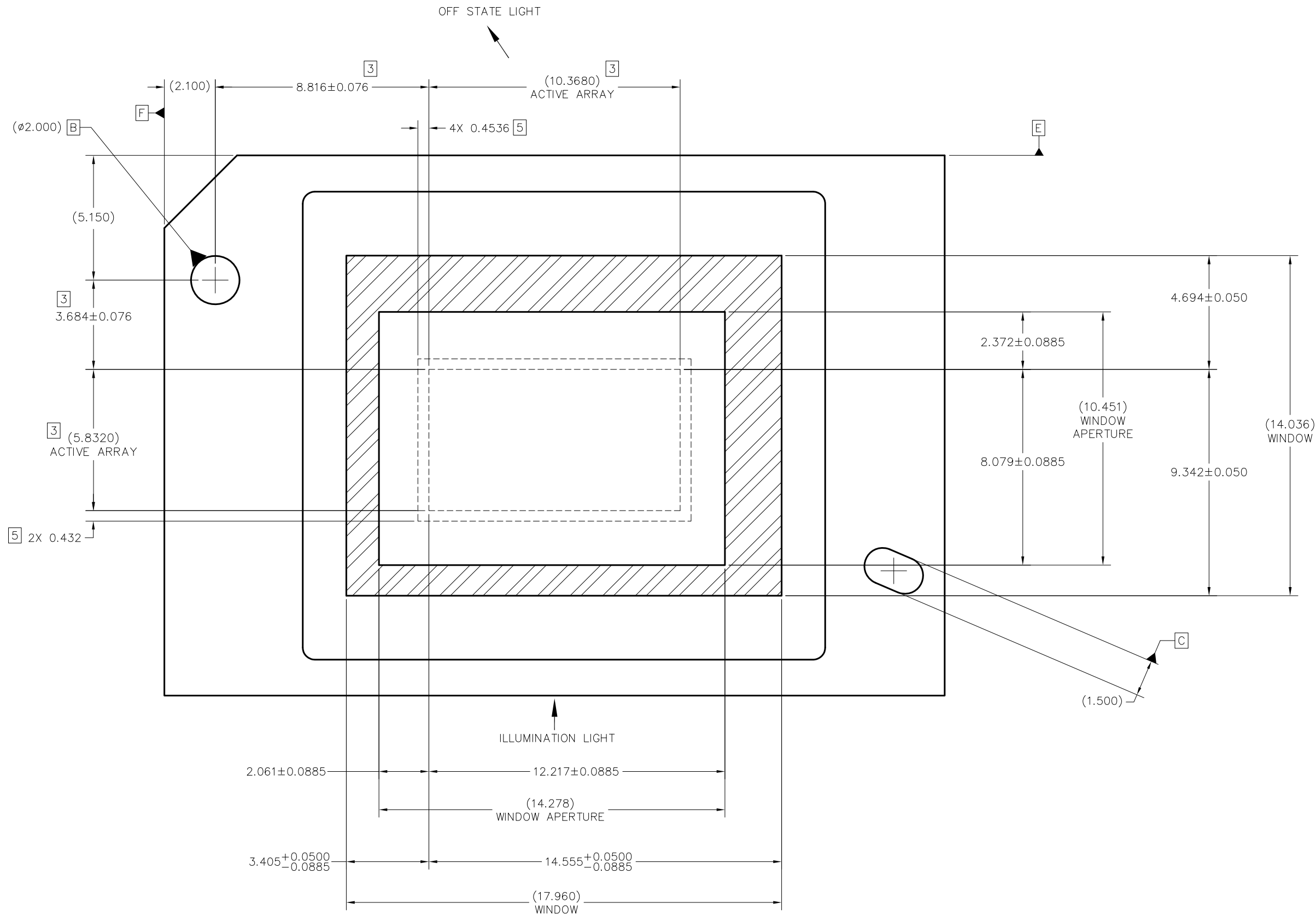
SECTION C-C
DATUM B
SCALE 16/1



VIEW B
DATUMS AND ENCAPSULANT ALLOWABLE AREA
SCALE 8/1

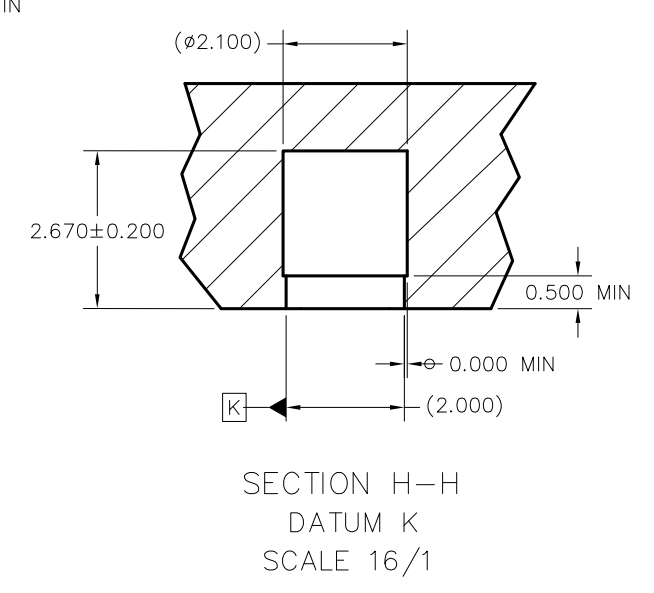
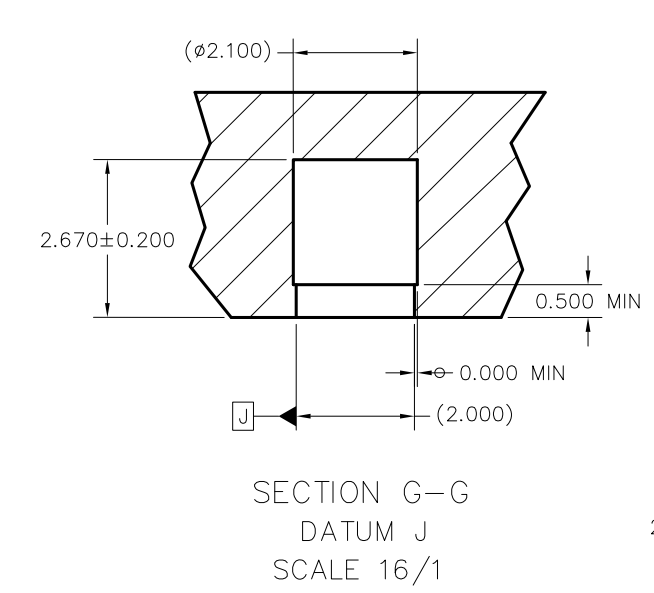
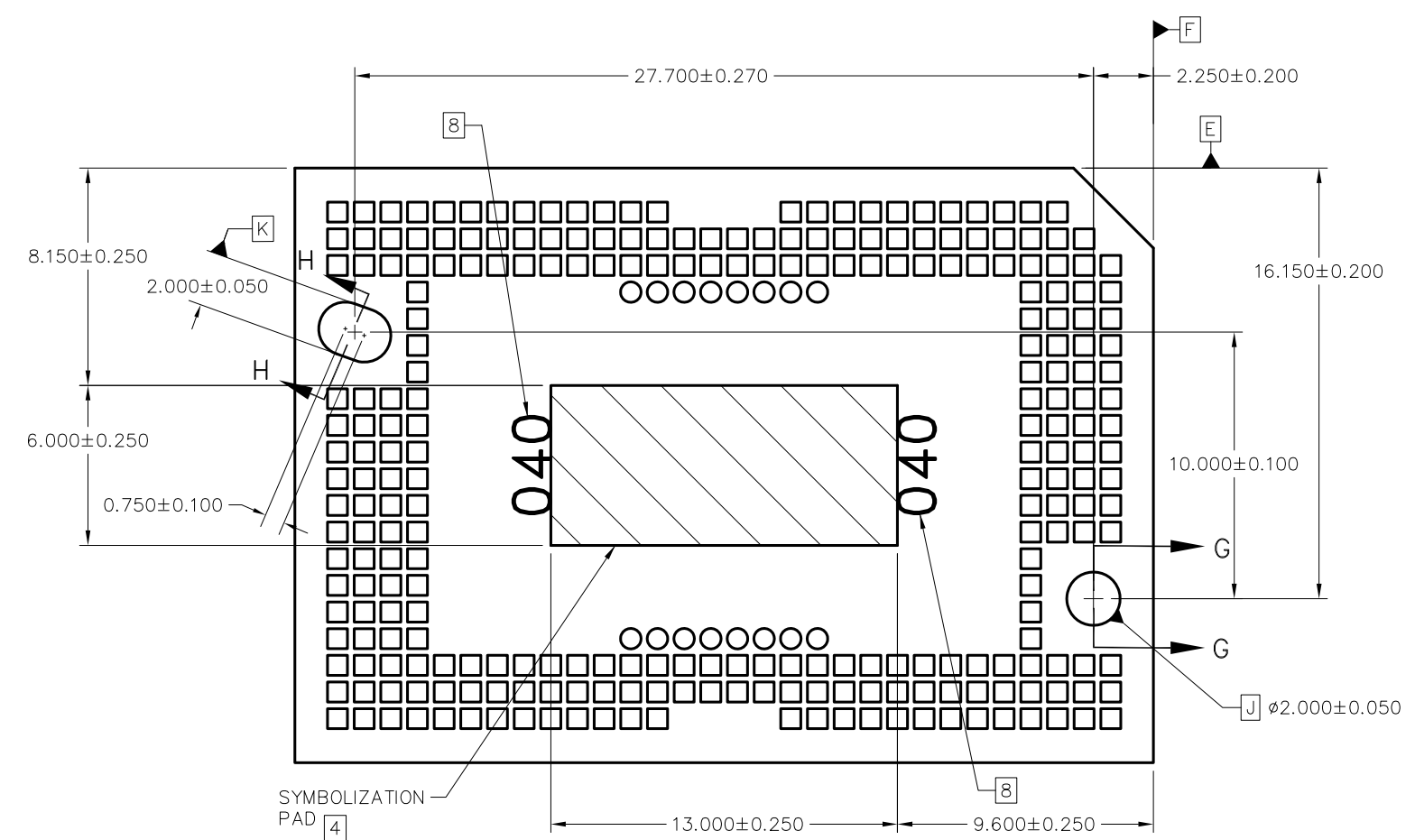


SECTION D-D
DATUM C
SCALE 16/1

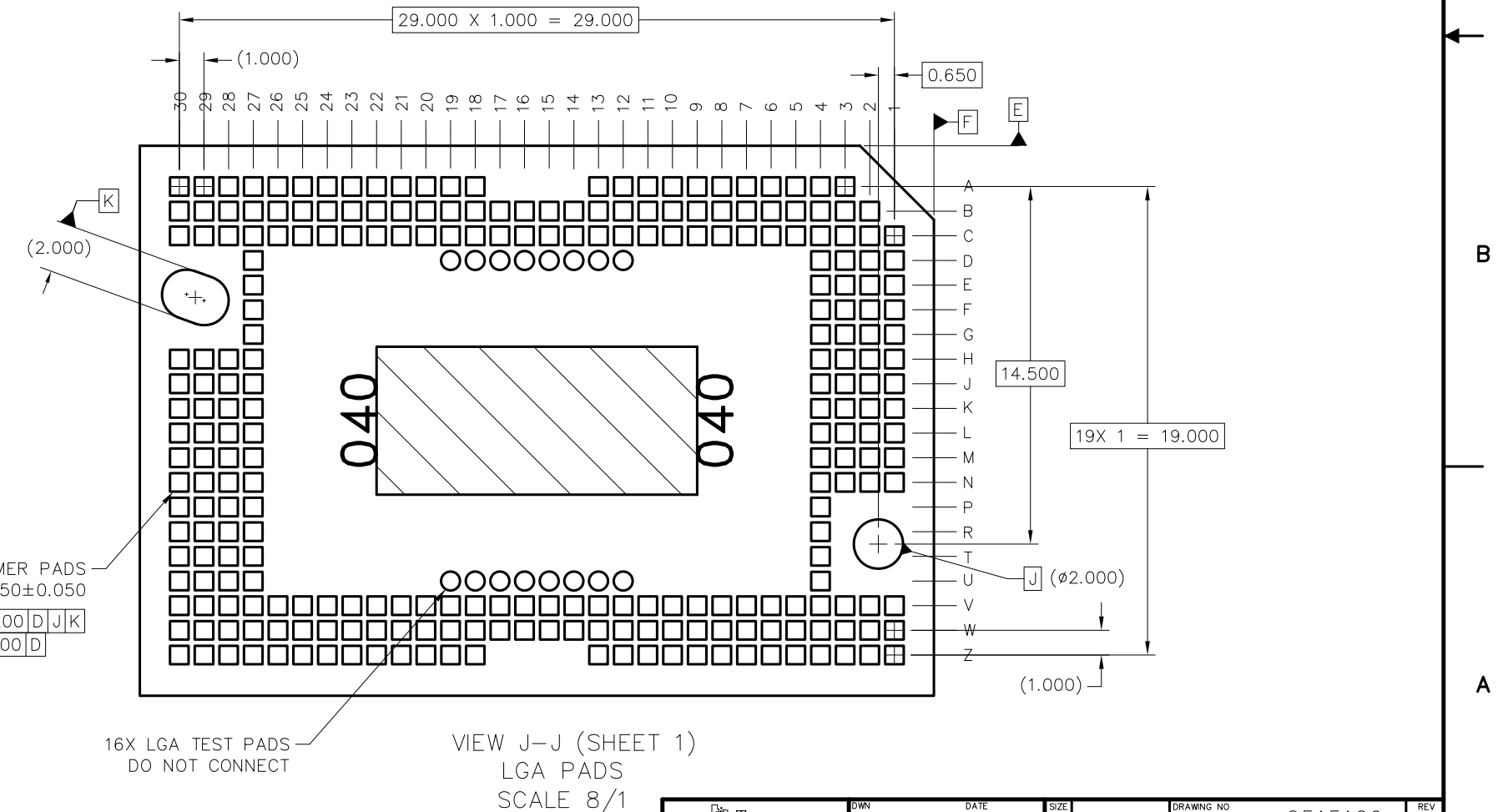


VIEW E (SHEET 1)
 DMD WINDOW AND ACTIVE ARRAY
 SCALE 12:1

 TEXAS INSTRUMENTS Dallas, Texas	DWN	DATE	SIZE	DRAWING NO	REV
	ISSUE DATE	SCALE	4/1	2515169	B
				SHEET	3



VIEW F-F (SHEET 1)
DATUMS J AND K, SYMBOLIZATION PAD
SCALE 8/1



VIEW J-J (SHEET 1)
LGA PADS
SCALE 8/1

257X LGA CUSTOMER PADS
0.750±0.050 X 0.750±0.050

16X LGA TEST PADS
DO NOT CONNECT

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